

Conference Agenda

Wednesday, 26 August	
Conference Room 14B	
09:00-09:40	Conference Opening & Award Ceremony Conference Director: Leo Lorenz, ECPE, DE
Conference Room 14B	
09:40-10:20	Keynote 1 Challenges and Innovations in Data Center Power Systems to Meet the AI Power Demand Speaker: Dehong Xu, Zhejiang University Chair: Leo Lorenz, ECPE, DE
Tea Break	
Conference Room 14B	
10:35-12:25	Special Session 1 Power Supply for AI Data Center Chair: Yenan Chen, Zhejiang University
Lunch Break & Room Change	
Poster Dialogue Session	
13:30-15:00	Poster Dialogue Session 1 Power Devices Chair: Yijen Chan, Cynotec Co., Ltd, TW, CN Haihui Luo, Zhuzhou CRRR Times Semiconductor, CN
	Poster Dialogue Session 2 Power Devices, Packaging and Reliability Chair: Yong Kang, Huazhong University of Science and Technology, CN Wei Jing, Semikron Danfoss, CN
	Poster Dialogue Session 3 Smart Grid and AI Chair: Miao Zhu, Shanghai Jiao Tong University, CN Teng Liu, China Southern Power Grid Electric Power Research Institute, CN
15:00-16:40	Conference Room 14B
	Oral Session 1 WBG Power Semiconductor Devices Chair: Bo Zhang, University of Electronic Science and Technology of China, CN Masahiro Sasaki, Fuji Electric Co., Ltd., JP
Conference Room 14A	
	Oral Session 2 High Efficiency Power Converter Chair: Teng Wu, Schneider Electric, CN Min Chen, Zhejiang University, CN
Thursday, August 27	
Conference Room 14B	
09:30-10:10	Keynote 2 Semiconductor contribution to performance & efficiency of Automotive Traction Inverters Speaker: Mark Nils Muenzer, Infineon Technologies AG Chair: Gourab Majumdar, Mitsubishi Electric Corporation, JP
Coffee Break & Room Change	
10:25-12:15	Conference Room 14B
	Special Session 2 AI in Power Electronics Chair: Jianing Wang, Hefei University of Technology
Conference Room 14A	
	Oral Session 3 Advanced Power Semiconductor Devices Technology Chair: Norbert Pluschke, CN-iCuTech, HKSAR, CN Yi Tang, Starpower Semiconductor, CN
Lunch Break	
Poster Dialogue Session	
13:30-15:00	Poster Dialogue Session 4 High Performance Power Conversion Chair: Lie Xu, Tsinghua University, CN TBD
	Poster Dialogue Session 5 Motor Drive & Motion Control Chair: Jinsong Kang, Tongji University, CN Gaosheng Song, Mitsubishi Electric & Electronics (Shanghai) Co., Ltd., CN
	Poster Dialogue Session 6 Automotive Power Electronics and Electrified Transportation Chair: Guoqiang Zhang, Harbin Institute of Technology, CN Gang Yao, Shanghai Maritime University, CN
15:00-16:40	Conference Room 14B
	Oral Session 4 AI in Power Electronics Chair: Jinjun Liu, Xi'an Jiaotong University, CN Lifeng Chen, Infineon Technologies, CN
Conference Room 14A	
	Oral Session 5 Packaging and Reliability for Power Semiconductors Chair: Naoto Fujishima, Fuji Electric, JP Xuhui Wen, Institute of Electrical Engineering, Chinese Academy of Sciences, CN
Friday, August 28	
Conference Room 14B	
09:00-09:40	Keynote 3 TBD Speaker: Junsheng Wei, BYD Company Limited, CN Chair:
09:40-10:20	Keynote 4 Enabling the Medium-Voltage Revolution: Innovations in 10kV SiC Power Packaging Platforms Speaker: Ziyang Gao, Hong Kong Microelectronics Research and Development Institute, CN Chair: Dong Li, Infineon Technologies Asia Pacific Pte Ltd, SG
Coffee Break & Room Change	
10:35-12:50	Conference Room 14B
	Oral Session 6 Motor Drives and Electrified Transportation Chair: Yongdong Li, Tsinghua University, CN Dapeng Zheng, Shenzhen Hopewind Electric, CN
Conference Room 14A	
	Oral Session 7 Power Electronics for Smart Grid Chair: Meiqin Mao, Hefei University of Technology, CN Jianping Ying, Delta Electronics, CN
Lunch Break	
The PCIM Asia Shenzhen Tour	